TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

# 2SK3567

### **Switching Regulator Applications**

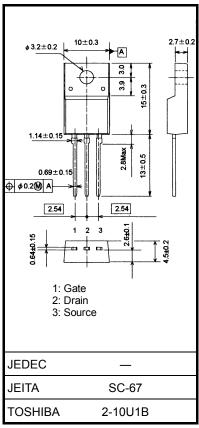
Unit: mm

- Low drain-source ON resistance: RDS (ON) =  $1.7 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 2.5S$  (typ.)
- Low leakage current:  $I_{DSS} = 100 \, \mu \, A \, (V_{DS} = 600 \, V)$
- Enhancement mode:  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

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## Absolute Maximum Ratings (Ta = 25°C)

| Characteristics                                      |                              | Symbol           | Rating  | Unit |  |
|--|------------------------------|------------------|---------|------|--|
| Drain-source voltage                                 |                              | $V_{DSS}$        | 600     | V    |  |
| Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ ) |                              | $V_{DGR}$        | 600     | V    |  |
| Gate-source voltage                                  |                              | V <sub>GSS</sub> | ±30     | V    |  |
| Drain current  | DC (Note 1)                  | I <sub>D</sub>   | 3.5     |      |  |
|  | Pulse (t = 1 ms)<br>(Note 1) | I <sub>DP</sub>  | 14      | Α    |  |
| Drain power dissipation (Tc = 25°C)                  |                              | PD               | 35      | W    |  |
| Single pulse avalanche energy (Note 2)               |                              | E <sub>AS</sub>  | 201     | mJ   |  |
| Avalanche current                                    |                              | I <sub>AR</sub>  | 3.5     | Α    |  |
| Repetitive avalanche energy (Note 3)                 |                              | E <sub>AR</sub>  | 3.5     | mJ   |  |
| Channel temperature                                  |                              | T <sub>ch</sub>  | 150     | °C   |  |
| Storage temperature range                            |                              | T <sub>stg</sub> | -55~150 | °C   |  |

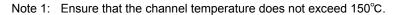


Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

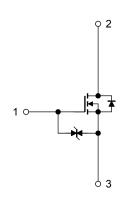
| Characteristics                        | Symbol                 | Max  | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case    | R <sub>th (ch-c)</sub> | 3.57 | °C/W |
| Thermal resistance, channel to ambient | R <sub>th (ch-a)</sub> | 62.5 | °C/W |



Note 2: 
$$V_{DD} = 90 \text{ V}$$
,  $T_{ch} = 25^{\circ}\text{C}(\text{initial})$ ,  $L = 28.8 \text{ mH}$ ,  $I_{AR} = 3.5 \text{ A}$ ,  $R_G = 25 \Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.





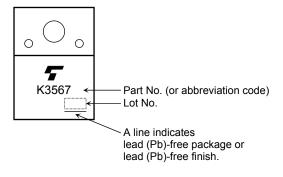
## **Electrical Characteristics (Ta = 25°C)**

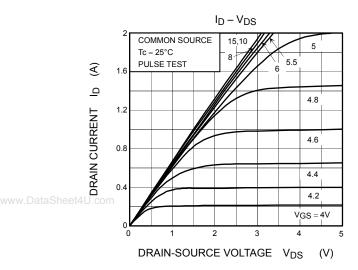
| Chara                        | acteristics                       | Symbol               | Test Condition  | Min | Тур. | Max | Unit |
|------------------------------|-----------------------------------|----------------------|---|-----|------|-----|------|
| Gate leakage cur             | rent                              | I <sub>GSS</sub>     | $V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$                         | _   | _    | ±10 | μА   |
| Gate-source brea             | ıkdown voltage                    | V (BR) GSS           | $I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$                                  | ±30 | _    | _   | V    |
| Drain cut-off curre          | ent                               | I <sub>DSS</sub>     | V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V                            |     | _    | 100 | μА   |
| Drain-source brea            | akdown voltage                    | V (BR) DSS           | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V                             | 600 | _    | _   | V    |
| Gate threshold vo            | oltage                            | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA                             | 2.0 | _    | 4.0 | V    |
| Drain-source ON              | resistance                        | R <sub>DS</sub> (ON) | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.8 A                            |     | 1.7  | 2.2 | Ω    |
| Forward transfer             | admittance                        | Y <sub>fs</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.8 A                            | 0.7 | 2.5  | _   | S    |
| Input capacitance            | nput capacitance C <sub>iss</sub> |                      |   |     | 550  | _   |      |
| Reverse transfer capacitance |                                   | C <sub>rss</sub>     | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz                  |     | 6    | _   | pF   |
| Output capacitance           |                                   | Coss                 |   |     | 60   | _   |      |
| Switching time               | Rise time                         | t <sub>r</sub>       | $V_{GS}$ $V_{D} \simeq 200 \text{ V}$                                     | _   | 12   | _   |      |
|                              | Turn-on time                      | t <sub>on</sub>      |   | _   | 45   | _   |      |
|                              | Fall time                         | t <sub>f</sub>       |   | _   | 13   | _   | ns   |
|                              | Turn-off time                     | t <sub>off</sub>     | Duty $\leq$ 1%, $t_W = 10 \ \mu s$  | _   | 80   | _   |      |
| Total gate charge            |                                   | Qg                   |   | _   | 16   | _   |      |
| Gate-source charge           |                                   | Qgs                  | $V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}$ | _   | 10   | _   | nC   |
| Gate-drain charge            |                                   | Q <sub>gd</sub>      |   | _   | 6    |     |      |

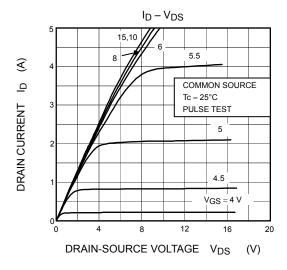
Source-Drain Ratings and Characteristics (Ta = 25°C)

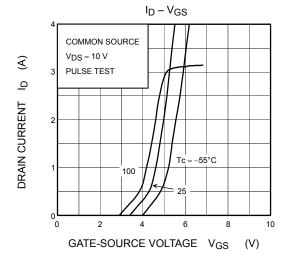
| Characteristics                           | Symbol           | Test Condition                                  | Min | Тур. | Max  | Unit |
|---|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | _   | _   | _    | 3.5  | Α    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> | _   | _   | _    | 14   | Α    |
| Forward voltage (diode)                   | V <sub>DSF</sub> | $I_{DR} = 3.5 \text{ A}, V_{GS} = 0 \text{ V}$  | _   | _    | -1.7 | V    |
| Reverse recovery time                     | t <sub>rr</sub>  | $I_{DR} = 3.5 \text{ A}, V_{GS} = 0 \text{ V},$ |     | 1400 | _    | ns   |
| Reverse recovery charge                   | Q <sub>rr</sub>  | dI <sub>DR</sub> /dt = 100 A/μs                 |     | 9.0  | _    | μС   |

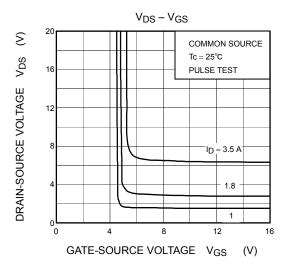
# Marking

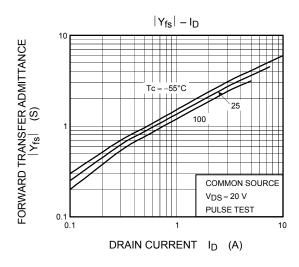


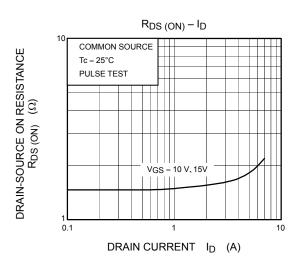












RDS (ON) - TC

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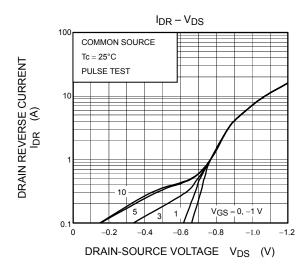
COMMON SOURCE
VGS = 10 V
PULSE TEST

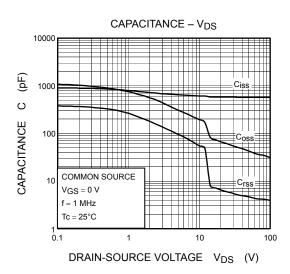
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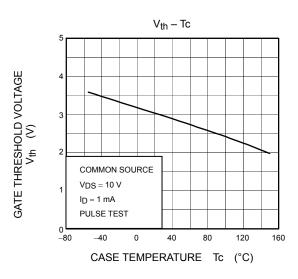
COMMON SOURCE
VGS = 10 V
PULSE TEST

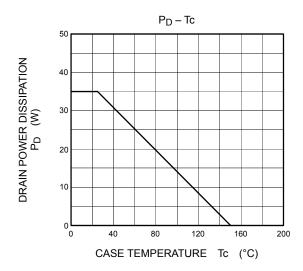
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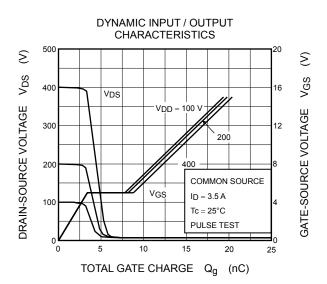
CASE TEMPERATURE TC (°C)

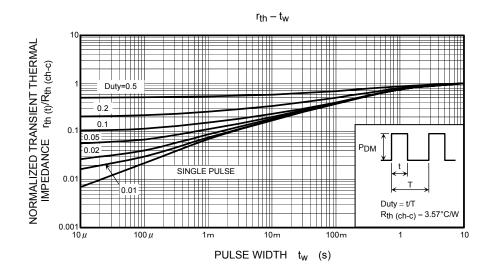




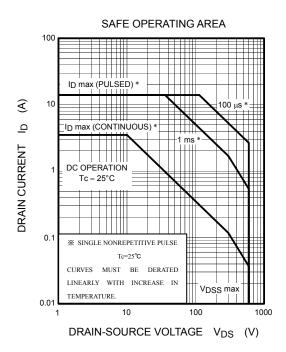


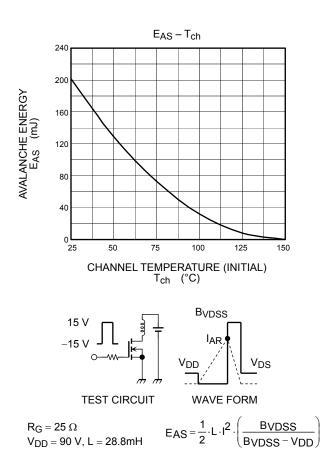






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